

Gold Plating

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Common Name	Also Known as	Typical Bath Constituents	Power Supply Recommendations	Typical Pulse Settings (if Used)	Typical Operating Parameters
Alkaline Non-Cyanide Gold	Soft Gold	Gold (8-12 g/L)	<1% ripple	High Frequency (HFP); Do Not Use Low Frequency Pulse (LFP)	Anodes: Platinum-Clad Columbium or Titanium (316 SS may be used if deposit purity isn't critical)
		Conducting Salt (25-85 g/L)	Amp-hr meter (gold metal additions based on A-hr meter readings)	Duty Cycle: 10% on a resistive seed layer or 70% on conductive metal	Heaters: Derated Titanium, Quartz, 316 SS
		Additive (30-60 g/L)	Pulse Recommended	10% Duty Cycle: 0.1 ms ON Time 70% Duty Cycle: 0.7 ms ON Time	Filter Continuously
		Thallium	Totalizer (tracks gold usage to prevent misuse or theft)	10% Duty Cycle: 0.9 ms OFF Time 70% Duty Cycle: 0.3 ms ON Time	Carbon Treat (Sensitive to Organics)
					Agitation: Moderate to Vigorous
					Operating temp: 95 to 130 F (120 F Nominal)
					Typical pH (range): 9.2 to 9.8 (9.5 nominal)
					Output Voltage (Power Supply Max Rating): 6 VDC
					Current Density: 1-5 ASF (0.1-0.5 ASD)